

1

2

3

DESCRIPTION

The IS341W Photocoupler is ideally suited for driving power IGBTs and MOSFETs used in inverters of motor control and of power supply system. It contains an AlGaAs LED optically coupled to an integrated circuit with a power output stage. The high peak output current of 3.0A is capable to direct drive IGBT with ratings up to 1200 V/100 A. For IGBTs with higher ratings, IS341W can be used to drive a discrete power stage which drives the IGBT gate.

The device is supplied in Stretched SO6 package with wide lead separation.

FEATURES

- 3.0A Maximum Peak Output Current
- 2.5A Minimum Peak Output Current
- Rail-to-Rail Output Voltage
- 20kV/µs Minimum Common Mode Rejection at V_{CM} 1500V
- Maximum Propagation Delay 200ns
- Maximum Propagation Delay Difference 100ns
- Wide Operating Voltage Range V_{CC} 15 to 30 V
- Under Voltage Lock Out (UVLO) Protection with Hysteresis
- Guaranteed Performance over Temperature Range - 40°C to +105°C
- MSL Level 1
- Lead Free and RoHS Compliant
- Safety Approvals Pending

APPLICATIONS

- IGBT/MOSFET Gate Drive
- **UPS**
- Industrial Inverters
- Switching Power Supplies
- AC Brushless and DC Motor Drives

ORDER INFORMATION

Supplied in Tape & Reel

Anode 6 NC Cathode 5 $GND(V_{EE})$

4

 V_0

 V_{CC}

A 0.1µF bypass Capacitor must be connected between Pins 6 and 4.

ABSOLUTE MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Stresses exceeding the absolute maximum ratings can cause permanent damage to the device.

Exposure to absolute maximum ratings for long periods of time can adversely affect reliability.

Forward Current	25mA
Forward Peak Current (Pulse Width ≤ 1µs, 300pps)	1.0A
Reverse Voltage	5V
Forward Current Rise / Fall Time	500ns
Power dissipation	45mW

Output	
High Level Peak Output Current Exponential waveform. Pulse width ≤ 0.3 µs, f ≤ 15 kHz	3.0A
Low Level Peak Output Current Exponential waveform. Pulse width ≤ 0.3 µs, f ≤ 15 kHz	3.0A
Supply Voltage (V _{CC} – V _{EE})	35V
Output Voltage	V_{CC}
Power Dissipation	700mW

Total Package

Isolation Voltage	$5000V_{RMS}$
Total Power Dissipation	745mW
Operating Temperature	-40 to 105 °C
Storage Temperature	-55 to 125 °C
Lead Soldering Temperature (10s)	260°C

ISOCOM COMPONENTS 2004 LTD

Unit 25B, Park View Road West, Park View Industrial Estate Hartlepool, Cleveland, TS25 1PE, United Kingdom Tel: +44 (0)1429 863 609 Fax: +44 (0)1429 863 581 e-mail: sales@isocom.co.uk

http://www.isocom.com

ISOCOM COMPONENTS ASIA LTD

Hong Kong Office, Block A, 8/F, Wah Hing Industrial mansion, 36 Tai Yau Street, San Po Kong, Kowloon, Hong Kong. Tel: +852 2995 9217 Fax: +852 8161 6292 e-mail: sales@isocom.com.hk



Truth Table

LED	V _{CC} – GND (Turn ON, +ve going)	V _{CC} – GND (Turn OFF –ve going)	Vo
OFF	0 – 30V	0 – 30V	LOW
ON	0 – 11.0V	0 – 9.5V	LOW
ON	11.0 – 13.5V	9.5 – 12.0V	TRANSITION
ON	13.5 – 30V	12 – 30V	HIGH

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
Operating Temperature	T_{A}	- 40	105	°C
Supply Voltage	$V_{CC} - V_{EE}$	15	30	V
Input Current (ON)	$I_{F(ON)}$	7	16	mA
Input Voltage (OFF)	$V_{F(OFF)}$	-3.0	0.8	V



INPUT

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward Voltage	V_{F}	$I_F = 10 \text{mA}$	1.2	1.37	1.8	V
Forward Voltage Temperature Coefficient	$\Delta V_F/\Delta T$	$I_F = 10 \text{mA}$		-1.237		mV/°C
Reverse Voltage	V_R	$I_R = 10\mu A$	5			V
Input Threshold Current (Low to High)	I_{FLH}	$V_{CC} = 30V$ $V_{O} > 5V$		1.8	5	mA
Input Threshold Voltage (High to Low)	$ m V_{FHL}$	$V_{CC} = 30V$ $V_{O} < 5V$	0.8			V
Input Capacitance	C_{IN}	$V_F = 0V$, $f = 1MHz$		33		pF

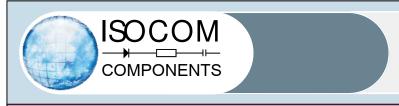
OUTPUT

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
High Level Supply Current	I _{CCH}	$I_F = 10$ mA, $V_{CC} = 30$ V $V_O = O$ pen		2.4	3.5	mA
Low Level Supply Current	I _{CCL}	$I_F = 0mA, V_{CC} = 30V$ $V_O = Open$		2.5	3.5	mA
High Level Output Current	I_{OH}	$V_O = V_{CC} - 1.5V$ Pulse Width = $50\mu s$			-1.0	A
		$\begin{aligned} V_{\rm O} &= V_{\rm CC} - 4V \\ \text{Pulse Width} &= 10 \mu \text{s} \end{aligned}$			-2.5	
Low Level Output Current	I_{OL}	$V_O = V_{EE} + 1.5V$ Pulse Width = $50\mu s$	1.0			A
		$V_{\rm O} = V_{\rm EE} + 4V$ Pulse Width = $10\mu s$	2.5			
High Level Output Voltage	V _{OH}	$I_F = 10 \text{mA}, I_O = -100 \text{mA}$	V _{CC} -0.3	$V_{CC} = 0.1$		V
Low Level Output Voltage	V _{OL}	$I_F = 0mA, I_O = 100mA$		$V_{EE} + 0.1$	V _{EE} +0.25	V
UVLO Threshold	V _{UVLO+}	$V_{O} > 5V, I_{F} = 10mA$	11.0	12.7	13.5	V
	V _{UVLO-}	$V_{O} < 5V, I_{F} = 10mA$	9.5	11.2	12.0	V
UVLO Hysteresis	UVLO _{HYS}			1.5		V



SWITCHING

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Propagation Delay Time to High Output Level	$t_{\rm PLH}$	$I_F = 7 \text{ to } 16\text{mA},$ $V_{CC} = 15 \text{ to } 30\text{V},$	50	130	200	ns
Propagation Delay Time to Low Output Level	$t_{ m PHL}$	$V_{EE} = 0V$ $Rg = 10\Omega$, $Cg = 25nF$,	50	130	200	
Pulse Width Distortion t _{PHL} - t _{PLH} for any given Device	PWD	f = 10kHz, Duty Cycle = 50%		5	70	
Propagation Delay Difference between any two Devices	PDD		-100		100	
Output Rise Time (10% to 90%)	t _r			35		
Output Fall Time (90% to 10%)	t_{f}			35		
Common Mode Transient Immunity at High Output Level	CM_{H}	$I_F = 10 \text{ to } 16\text{mA},$ $V_{CC} = 30\text{V}$ $V_{CM} = 1500\text{V},$ $T_A = 25^{\circ}\text{C}$	20	25		kV/μs
Common Mode Transient Immunity at Low Output Level	CM _L	$V_F = 0V,$ $V_{CC} = 30V$ $V_{CM} = 1500V,$ $T_A = 25^{\circ}C$	20	25		kV/μs



$\begin{array}{c} \textbf{ELECTRICAL CHARACTERISTICS} \text{ (Typical Values at V}_{\text{CC}} - \text{V}_{\text{EE}} = 10\text{V to } 30\text{V and T}_{\text{A}} = 25^{\circ}\text{C}, \\ \text{Minimum and Maximum Values at Recommended Operating Conditions,} \end{array}$

unless otherwise specified)

ISOLATION

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Insulation Voltage	$V_{\rm ISO}$	RH $\leq 40\%$ to 60%, t = 1 min, T _A = 25°C	5000			V
Input - Output Resistance	R _{I-O}	$V_{\text{I-O}} = 500 \text{VDC}$		10 ¹²		Ω
Input - Output Capacitance	$C_{\text{I-O}}$	$f = 1MHz$, $T_A = 25$ °C		0.92		pF

Note:

- 1. A 0.1uF or bigger bypass capacitor must be connected across pin 6 and pin 4.
- 2. PDD is the difference of Propagation Delays between any two IS341W devices under same test conditions.
- ${\rm CM_{H}}$, Common Mode Transient Immunity in High stage is the maximum tolerable positive ${\rm dV_{CM}}/{\rm dt}$ on the 3. leading edge of the common mode impulse signal, V_{CM}, to assure that the output will remain high $(V_0 > 15V)$.
- CM_L, Common Mode Transient Immunity in Low stage is the maximum tolerable negative dV_{CM}/dt on the 4. trailing edge of the common mode impulse signal, V_{CM}, to assure that the output will remain low $(V_0 < 1V)$.



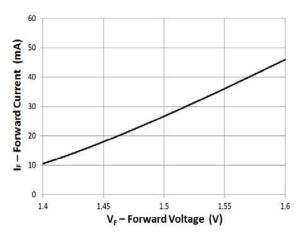


Fig 1 Forward Current vs Forward Voltage

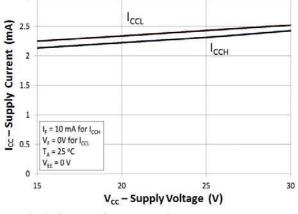


Fig 2 Supply Current vs Supply Voltage

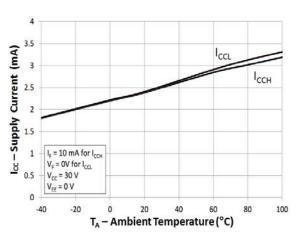


Fig 3 Supply Current vs Ambient Temperature

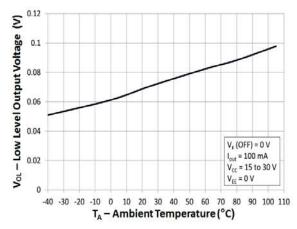


Fig 4 Low Level Output Voltage vs Ambient temperature

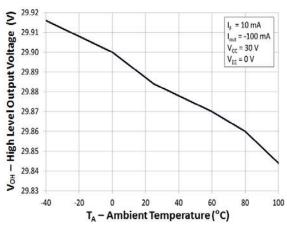


Fig 5 High Level Output Voltage vs Ambient Temperature

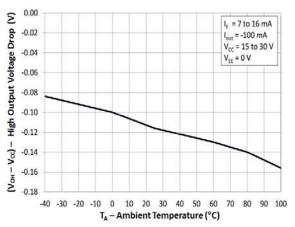


Fig 6 High Output Voltage Drop vs Ambient Temperature



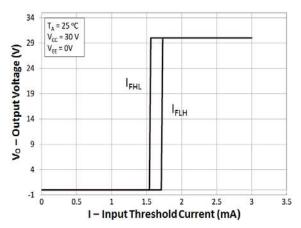


Fig 7 I_{FLH} Hysteresis

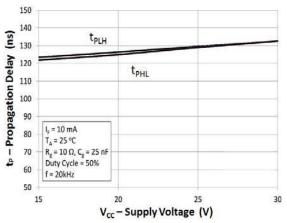


Fig 9 Propagation Delay vs Supply Voltage

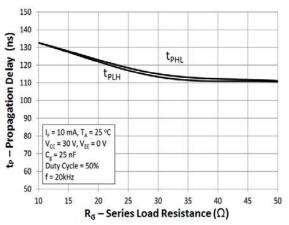


Fig 11 Propagation Delay vs Series Load Resistance

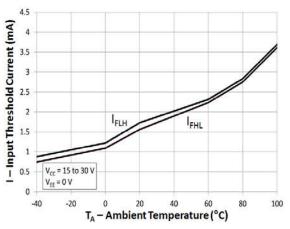


Fig 8 Input Threshold Current vs Ambient Temperature

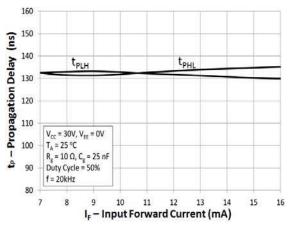


Fig 10 Propagation Delay vs Forward Current

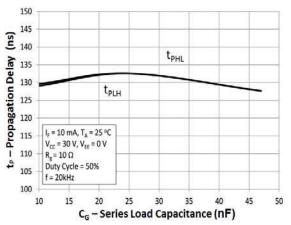


Fig 12 Propagation Delay vs Series Load Capacitance



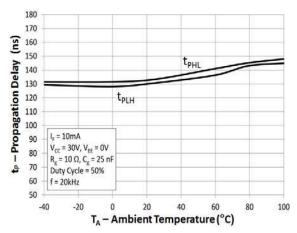
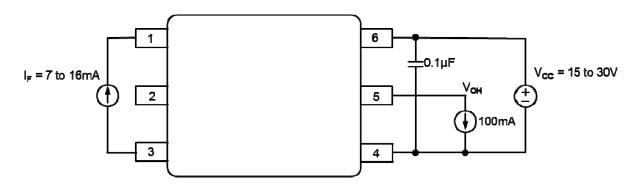
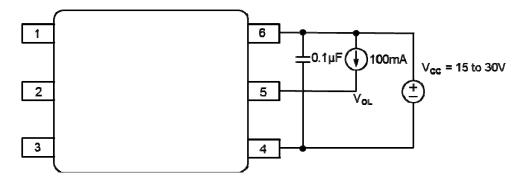


Fig 13 Propagation Delay vs Ambient Temperature

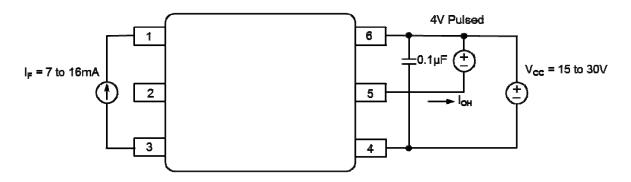


 V_{OH} Test Circuit

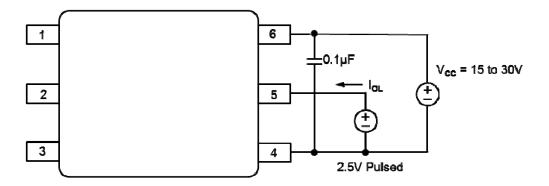


 $V_{OL} \ Test \ Circuit$

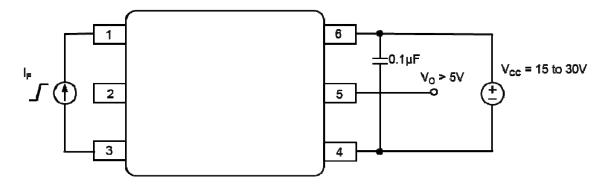




I_{OH} Test Circuit

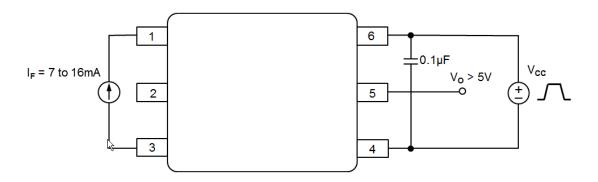


I_{OL} Test Circuit

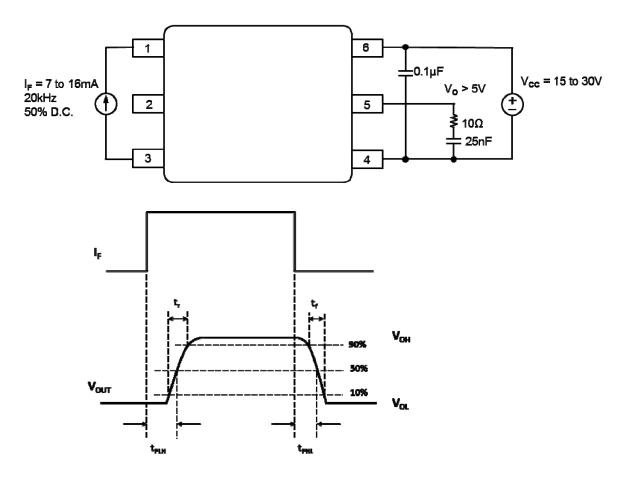


I_{FLH} Test Circuit



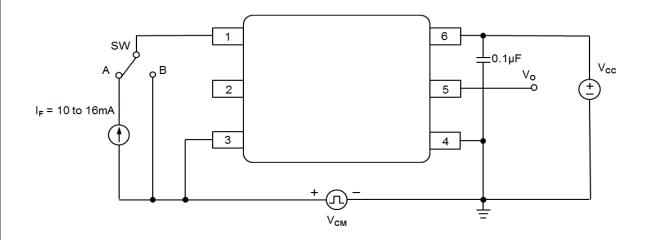


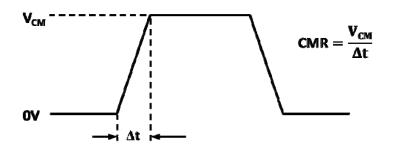
UVLO Test Circuit

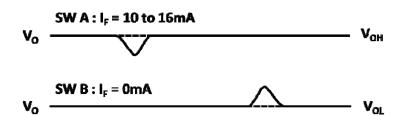


 $t_{r},\,t_{f},\,t_{PLH}$ and t_{PHL} Test Circuit and Waveform









CMR Test Circuit and Waveform



ORDER INFORMATION

	IS341W				
After PN	PN	Description	Packing quantity		
None	IS341W	Stretched SO6 Wide Lead Separation	1000 pcs per reel		

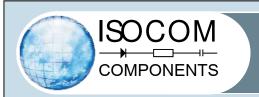
DEVICE MARKING



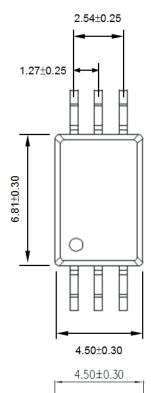
IS341W denotes Device Part Number

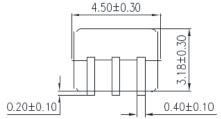
I denotes Isocom

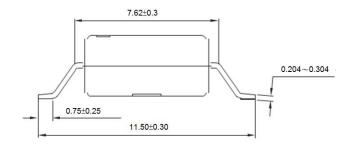
YY denotes 2 digit Year code WW denotes 2 digit Week code



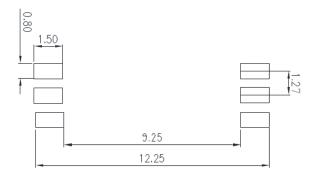
PACKAGE DIMENSIONS (mm)





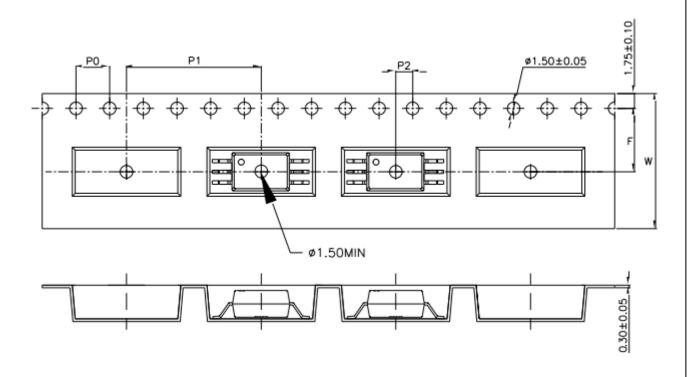


RECOMMENDED PAD LAYPUT (mm)





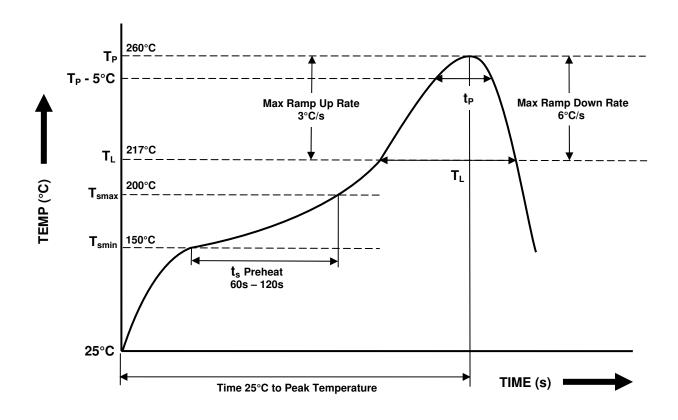
TAPE AND REEL PACKAGING



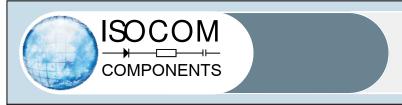
Description	Symbol	Dimension mm (inch)
Tape Width	W	16 ± 0.3 (0.63)
Pitch of Sprocket Holes	P ₀	4 ± 0.1 (0.16)
Distance of Compartment to Sprocket Holes	F	7.5 ± 0.1 (0.3)
Distance of Compartment to Sprocket Holes	P ₂	2 ± 0.1 (0.079)
Distance of Compartment to Compartment	P ₁	16 ± 0.1 (0.63)



IR REFLOW SOLDERING TEMPERATURE PROFILE (One Time Reflow Soldering is Recommended)



Profile Details	Conditions
$ \begin{array}{l} \textbf{Preheat} \\ \textbf{- Min Temperature } (T_{SMIN}) \\ \textbf{- Max Temperature } (T_{SMAX}) \\ \textbf{- Time } T_{SMIN} \text{ to } T_{SMAX} \left(t_s\right) \end{array} $	150°C 200°C 60s - 120s
$\begin{tabular}{ll} \textbf{Soldering Zone} \\ - & \begin{tabular}{ll} - & \begin{tabular}{ll} \textbf{Peak Temperature } & \begin{tabular}{ll} - & \begin{tabular}{ll} \textbf{Peak Temperature } & \begin{tabular}{l$	260°C 10s max 217°C 30s max 60s - 100s 3°C/s max 6°C/s max
Average Ramp Up Rate (T _{smax} to T _P)	3°C/s max
Time 25°C to Peak Temperature	8 minutes max



NOTES:

- Isocom is continually improving the quality, reliability, function or design and Isocom reserves the right to make changes without further notices.
- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/application where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc., please contact our sales representatives.
- When requiring a device for any "specific" application, please contact our sales for advice.
- The contents described herein are subject to change without prior notice.
- Do not immerse device body in solder paste.



DISCLAIMER

ISOCOM is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing ISOCOM products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such ISOCOM products could cause loss of human life, bodily injury or damage to property.

In developing your designs, please ensure that ISOCOM products are used within specified operating ranges as set forth in the most recent ISOCOM products specifications.

The ISOCOM products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These ISOCOM products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation Instruments, traffic signal instruments. combustion control instruments, medical Instruments, all types of safety devices, etc.. Unintended Usage of ISOCOM products listed in this document shall be made at the customer's own risk. Gallium arsenide (GaAs) is a substance used in the products described in this document. GaAs dust and fumes are toxic. Do not break, cut or pulverize the product, or use chemicals to

dissolve them. When disposing of the products, follow the appropriate regulations. Do not dispose of the products with other industrial waste or with domestic garbage.

The products described in this document are subject to the foreign exchange and foreign trade laws.

The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by ISOCOM Components for any infringements of intellectual property or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any intellectual property or other rights of ISOCOM Components or others.

The information contained herein is subject to change without notice.